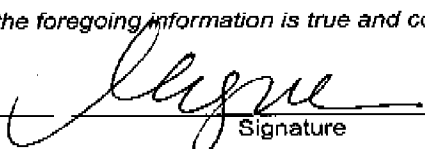


Form PTO-1595 (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002)		<b>RECORDATION FORM COVER SHEET</b> <b>PATENTS ONLY</b>		U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof					
1. Name of conveying party(ies): Atsushi Itsuki  Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			2. Name and address of receiving party(ies) Name: <u>Mitsubishi Materials Corporation</u> Internal Address: _____ Street Address: _____ 5-1, Otemachi 1-chome Chiyoda-ku, Tokyo JAPAN  Additional name(s) & address(es) attached: <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
3. Nature of Conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____ Execution Date: <u>March 2, 2004</u>			4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the new application is: _____ A. Patent Application No.(s): <u>10/764,273</u> B. Patent No.(s): _____ Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
5. Name and address of party to whom correspondence concerning document should be mailed: Name: <u>Joseph R. Robinson</u> <u>DARBY &amp; DARBY P.C.</u> Internal Address: <u>Atty. Dkt.: 09852/0200822-US0</u> Street Address: _____ <u>P.O. Box 5257</u>  City: <u>New York</u> State: <u>NY</u> Zip: <u>10150-5257</u>			6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 3.41) \$ <u>40.00</u> <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Authorized to be charged to credit card (Form 2038 enclosed) 8. Deposit account number: <u>04-0100</u> (Attach duplicate copy of this page if paying by deposit account)		
<b>DO NOT USE THIS SPACE</b>					
9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i>  <div style="display: flex; justify-content: space-between; align-items: flex-end;"> <div style="width: 40%;"> <u>Marie Gilfillan - 44,085</u>            Name of Person Signing         </div> <div style="width: 30%; text-align: center;">             Signature         </div> <div style="width: 20%; text-align: right;"> <u>June 18, 2004</u>            Date         </div> </div> <div style="text-align: right; margin-top: 10px;">         Total number of pages including cover sheet, attachments, and documents: <u>3</u> </div>					

Express Mail Label No.

Dated: \_\_\_\_\_

09852/0200822-USO

Attorney Docket No. \_\_\_\_\_

**ASSIGNMENT**

I/We, the inventor(s) named below [hereinafter referred to as the Assignor(s)], have made an invention entitled:

ORGANOMETALLIC COMPOUND, ITS SYNTHESIS METHOD, AND SOLUTION RAW MATERIAL AND METAL-CONTAINING THIN FILM CONTAINING THE SAME

for which application for Letters Patent of the United States was executed on \_\_\_\_\_  
herewith unless otherwise indicated below:

filed on January 23, 2004, Serial No. 10/764,273, and

(Full Name, Address, and Nationality of Assignee(s))

mitsubishi materials corporation

of 5-1, Otemachi 1-chome, Chiyoda-ku, Tokyo, Japan

[hereinafter referred to as the Assignee(s)], is/are desirous of securing the entire right, title, and interest in and to this invention, the application for United States Patent for this invention, and the Letters Patent to be issued upon this application;

Now, therefore, be it known that, for good and valuable consideration, the receipt of which from the Assignee(s) is hereby acknowledged, I/we, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee(s), its/their lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention in the name of the Assignee(s), its/their successors and assigns, in accordance with the terms of this assignment;

And I/we hereby further covenant and agree that I/we will, without further consideration, communicate with the Assignee(s), its/their successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful documents when called upon to do so, execute and deliver all documents that may be necessary or desirable to perfect the title to this invention in the name of the Assignee(s), its/their successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid the Assignee(s) and its/their successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such documents shall be borne by the Assignee(s), its/their successors and assigns.

Full name of (check one) <input checked="" type="checkbox"/> Sole or <input type="checkbox"/> First Assignor	
Signature <u>Atsushi Itsuki</u>	Date <u>March 2, 2004</u>
Type <u>Atsushi ITSUKI</u>	Citizenship <u>Japan</u>

Full name of Second Assignor, if any	
Signature _____	Date _____
Type _____	Citizenship _____

Full name of Third Assignor, if any	
Signature _____	Date _____
Type _____	Citizenship _____

Full name of Fourth Assignor, if any	
Signature _____	Date _____
Type _____	Citizenship _____

Full name of Fifth Assignor, if any	
Signature _____	Date _____
Type _____	Citizenship _____